Compliant with IEC 62474/ D9.00

Basic Substance	MICROCHIP Semiconductor Device Type: P7X 028 QFN 5x5x0.9mm Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				J-STD-609A Product Marking and/or Pkg. Labeling e3
State Control State Cont		,,,,	"Contained In"				28.43	(mg) Total	Mold Compound	% ot Total Weight	42.75
Figure Train Train Source Most Compound 1.54 2.41 2.43 3.53 3.54									· ·		1
Principle Search Tage Sectors Mail Compound 1,468 0,995 14,582 1,562 1											
Centro Biols											
Copport	Silica, vitreous (or fused)	7631-86-9	Mold Compound	1.154	0.768	11,543		Silica, vitreous (or fused)	7631-86-9	2.70	
Time	Carbon Black	1333-86-4	Mold Compound	0.128	0.085	1,283		Carbon Black	1333-86-4	0.30	
Share	Copper		Lead Frame						Total	100.00	2
Price Pric			Lead Frame				28.84	(mg) Total	Lead Frame	% of Total Weight	43.37
Chronium 7440-73 Leas Frame 0.108 0.072 1.084											
Silver											
Acrylic Peters											
SOC First Trade Secret Die Atlanch 2 0.265 0.176 2.603 0.176 2.603 0.176 2.603 0.176 2.603 0.176 2.603 0.176 2.603 0.176 0											
Epoxy Resin								Chromium			
Acytic Copolymer Priend Resin Priend Resin Priend Resin Trade Scoret Deed Siston 7440-21-3 Chip (Dis) To 7440-21-3 Chip (Dis)									1 4 4 4 4		
Principle (Resin Trade Secret Dea Allach 2 0.080 0.083 854 1.000							0.55				0.82
Doped Silcon PAG-97-5 Planty one-perfect with the properties of the properties with the above EU Directives has been verified via internal design controls, supplier declarations, and for analytical test data. **Perfect of the properties have been been under the total very supplier and properties have been been under the UL-94 Via manufacture of the properties have been provided by subcortreated in this form which the specific proportated substance, in any part of the protective that the unavoidable in the service of the protective from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology properties's howeving and balled as of the date of this societum, there is no credible reason to believe that the unavoidable impurity concernation of the chemical substance, if any, is required by Microchip ment the UL-94 Via flammanth, there is no credible reason to believe that the unavoidable impurity concernation of the chemical substance, if any, is required by Microchip ment the UL-94 Via flammanth, there is not credible reason to believe that the unavoidable impurity concernation of the chemical substance, if any, is required by Microchip ment the UL-94 Via flammanth, there is not credible reason to believe that the unavoidable impurity concernation of the chemical substance, if any, is required by Microchip ment the UL-94 Via flammanth, there is not credible reason to believe that the unavoidable impurity concernation of the chemical substance, if any, is required by Microchip ment the UL-94 Via flammanth, there is not credible reason to believe that the unavoidable impurity concernation of the chemical substance, if any, is required by Microchip ment the UL-94 Via flammanth, there is not credible reason to believe that the unavoidable impurity concerns for any requisitory scheme work wide. **Total*** **Doped Sikon** **Total*** **Doped Sikon** **Total** **Doped Gidd** **Total** **Doped Gidd** **Total** **Total** **Doped											
Poped Gold The T440-97-5 Palling on external last Dipm. 1 March 1 Transport and 1 1,380 Part 1 1								Acrylic Resin			
The Table Secret 17.38 1. To 18.40 Secret 1. Train Secret 1.											
O.065 g Total Mass semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/85/EU (88 June 2011) and 2015/86/3/EU (31 March 2015) pllance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. Hermical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology proparates' knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is seleve the threshold of regulatory concern for any regulatory scheme world-wide. In go compounds usually Microchip September 10 Microchip Technology in the control of regulatory concern for any regulatory scheme world-wide. In go compounds usually by Microchip manifolds and a test report at Microchip September 10 Microchip September							0.37				0.56
O.0665 G Total Mass semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003). & Directive 2011/85/EU (08 June 2011) and 2015/863/EU (31 March 2015) pliance with the above EU Directives has been verified via internal design controls, supplier declarations, and for analytical sets data. Total 100.00 Total 100.00 Total 100.00 Total Weight 8.35 Total (mg) Chip (bile) % of Total Weight 8.35 Total (mg) Total Weight 1.38 Deped Silcon 7440-21-3 100.00 Total Weight 1.38 Deped Silcon 7440-21-3	IIN	7440-31-5 Plating or									
semiconductor devices and its homogenous materials comply with EU Directives: 200295/EC (27 January 2003) & Directive 2011/85/EU (98 June 2011) and 2015/863/EU (31 March 2015) pliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. Total 100.00 Total Weight 8, 55 Total (mg) Chip (Die) % of Total Weight 8, 95 Total (mg) Chip (Die) % of Total Weight 1,35 Dioped Silicon 1,35 Total (mg) Total Weight 2,35 Total (mg) Total Weight 1,35 Total (mg) Total Weight 2,35 Total (mg) Total Weight		0.0005 -		100.000	66.500	1,000,000					
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below the threshold of regulatory concern for any regulatory scheme world-wide. In comploading pages/offerings/industries/chemicals/plastics/ In which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and in "relss" may be made from PVC plastic. Doped Slicon 7440-21-3 100. Doped Slicon 7440-2	2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero	,		ie 2011) and 20	713/803/E0 (31	March 2015)		Phenol Resin			
///Licon/global/eng/page/offerings/Industries/chemicals/plastics/ protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and in "reles" may be made from PVC plastic. Doped Selection Total 100.00	2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero	rnal design controls, supplier d	eclarations, and /or analytical test data.	·		,		Phenol Resin			
which mes beginner product is snipped are made from protyping children product is snipped are made from protyping children products in their mesters may be made from PVC plastic. In "relest" may b	2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero pliance with the above EU Directives has been verified via inter themical substance is absent from the list above, the chemical rporated's knowledge and belief as of the date of this documen below the threshold of regulatory concern for any regulatory sci	rnal design controls, supplier d substance is NOT an intentiona nt, there is no credible reason to theme world-wide.	eclarations, and for analytical test data. I ingredient in the semiconductor device and, to to be believe that the unavoidable impurity concentrat	he best of Micr ion of the chem	rochip Technol nical substance	logy	5.95		Total	100.00	8.95
nal packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the peleteness and accuracy of data in this form because it has been compiled based on the ranges provided by subcontract assemblers and raw material suppliers. Supplier mation is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is ided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of more provided by subcontract assemblers and raw material suppliers. Information is ided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of more provided in this form. Microchip's subcontract assemblers and raw material suppliers. Suppliers. Information is ided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of more provided in this form. Microchip's subcontract assemblers and raw material suppliers. Suppliers. Information is dided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of microchip's understance levels of material contained within silicon devices (silicon IC) in the finished parts. Doped Gold Total Wieght Total Doped Gold Total Weight Total Doped Gold Total Weight Total	2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero pliance with the above EU Directives has been verified via inter chemical substance is absent from the list above, the chemical rporated's knowledge and belief as of the date of this documen below the threshold of regulatory concern for any regulatory sci-	rnal design controls, supplier d substance is NOT an intention tt, there is no credible reason to theme world-wide. ility standard for plastics. You	eclarations, and for analytical test data. I ingredient in the semiconductor device and, to to be believe that the unavoidable impurity concentrat	he best of Micr ion of the chem	rochip Technol nical substance	logy	5.95	Total (mg)	Total Chip (Die) 7440-21-3	100.00 % of Total Weight	8.95
ided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales are knowledgement, and invoices. Inchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, pered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate compliance for semiconductor products. Inchip disclaims and invoices. Inchip disclaims are contained in Microchip's quotations, sales are sult of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate compliance for semiconductor products. Inchip disclaims are contained in Microchip's quotations, sales are contained in Microchip's quotations, and indirect content provided in Microchip's quotations, sales are contained in Microchip's quotations, sales are contained in Microchip's quotations, and indirect content provided in Microchip's quotations, and indir	2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero pliance with the above EU Directives has been verified via inter chemical substance is absent from the list above, the chemical rporated's knowledge and belief as of the date of this documen below the threshold of regulatory concern for any regulatory sci- ling compounds used by Microchip meet the UL94 V0 flammabi //ul.com/global/eng/pages/offerings/industries/chemicals/plasti	rnal design controls, supplier d substance is NOT an intention t, there is no credible reason to heme world-wide. illity standard for plastics. You ics/	eclarations, and /or analytical test data. I ingredient in the semiconductor device and, to to believe that the unavoidable impurity concentrate an access the UL iQTM family of databases to ob-	he best of Micr ion of the chem tain a test repo	rochip Technol nical substance ort at	logy e, if any, is	5.95	Total (mg)	Total Chip (Die) 7440-21-3	100.00 % of Total Weight	8.95
seried by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate ampliance for semiconductor products. 1.44	2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero pliance with the above EU Directives has been verified via intershemical substance is absent from the list above, the chemical reporated's knowledge and belief as of the date of this documen below the threshold of regulatory concern for any regulatory sciling compounds used by Microchip meet the UL94 V0 flammabi //ul.com/global/eng/pages/offerings/industries/chemicals/plastiprotective "tubes" in which the specific product is shipped are in "reels" may be made from PVC plastic. ochip Technology Incorporated believes the information in this nal packing materials is true and correct to the best of its know pleteness and accuracy of data in this form because it has beer mation is often protected from disclosure as trade secrets and ded only as estimates of the average weight of these parts and	ral design controls, supplier d substance is NOT an intentions it, there is no credible reason to heme world-wide. illity standard for plastics. You d ics/ made from polyvinyl chloride (it form concerning substances r wledge and belief, as of the date n compiled based on the range some information may not hay the average weight of anticipe	eclarations, and /or analytical test data. I ingredient in the semiconductor device and, to the believe that the unavoidable impurity concentrate an access the UL iQTM family of databases to observe the concentration of the concentration o	he best of Micrion of the chem tain a test repo e packing slip porated's semic orated cannot g d by raw materi aw material su	rochip Technol nical substance ort at on the outer be conductor devi juarantee the ial suppliers. S ppliers. Inform	logy e, if any, is oox and ices in their supplier nation is		Total (mg) Doped Silicon	Total Chip (Die) 7440-21-3 Total	100.00 % of Total Weight 100	
#Indeed package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at latest sVHC candidate list of ECHA which	2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero pliance with the above EU Directives has been verified via interschemical substance is absent from the list above, the chemical reporated's knowledge and belief as of the date of this documen below the threshold of regulatory concern for any regulatory scilling compounds used by Microchip meet the UL94 V0 flammabil/ful.com/global/eng/pages/offerings/industries/chemicals/plastiprotective "tubes" in which the specific product is shipped are ain "reels" may be made from PVC plastic. ochip Technology Incorporated believes the information in this nal packing materials is true and correct to the best of its know pleteness and accuracy of data in this form because it has beel mation is often protected from disclosure as trade secrets and died only as estimates of the average weight of these parts and ants, metals, and non-metal materials contained within silicon coochip Technology Incorporated does not provide any warranty,	rand design controls, supplier d substance is NOT an intentions it, there is no credible reason to theme world-wide. illity standard for plastics. You d ics/ made from polyvinyl chloride (form concerning substances r vledge and belief, as of the date n compiled based on the range some information may not hav the average weight of anticips devices (silicon IC) in the finish express or implied, with respe	eclarations, and /or analytical test data. I ingredient in the semiconductor device and, to the believe that the unavoidable impurity concentrate an access the UL iQTM family of databases to observe the concentration of the concentration o	the best of Micrion of the chemitain a test reported is semilo porated's semilo by raw material sujustimates do not the exclusive,	rochip Technol nical substance ort at on the outer be conductor devi juarantee the lal suppliers. S ppliers. Inform it include trace	logy i.e. if any, is foox and fices in their supplier foot is e levels of		Total (mg) Doped Silicon (mg) Total	Total Chip (Die) 7440-21-3 Total Wire Bond	100.00 % of Total Weight 100 100.00 % of Total Weight	
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